Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	604
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga40e-6ff1152i

LatticeSC/M Family Data Sheet Architecture

December 2008 **Data Sheet DS1004**

Architecture Overview

The LatticeSC architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR). The upper left and upper right corners of the devices contain SERDES blocks and their associated PCS blocks, as show in Figure 2-1.

Top left and top right corner of the device contain blocks of SERDES. Each block of SERDES contains four channels (quad). Each channel contains a single serializer and de-serializer, synchronization and word alignment logic. The SERDES quad connects with the Physical Coding Sub-layer (PCS) blocks that contain logic to simultaneously perform alignment, coding, de-coding and other functions. The SERDES quad block has separate supply, ground and reference voltage pins.

The PICs contain logic to facilitate the conditioning of signals to and from the I/O before they leave or enter the FPGA fabric. The block provides DDR and shift register capabilities that act as a gearbox between high speed I/O and the FPGA fabric. The blocks also contain programmable Adaptive Input Logic that adjusts the delay applied to signals as they enter the device to optimize setup and hold times and ensure robust performance.

sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM, ROM or FIFO. These blocks have dedicated logic to simplify the implementation of FIFOs.

The PFU, PIC and EBR blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. These blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

The corners contain the sysCLOCK Analog Phase Locked Loop (PLL) and Delay Locked Loop (DLL) Blocks. The PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeSC architecture provides eight analog PLLs per device and 12 DLLs. The DLLs provide a simple delay capability and can also be used to calibrate other delays within the device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The system bus simplifies the connections of the external microprocessor to the device for tasks such as SERDES and PCS configuration or interface to the general FPGA logic. The LatticeSC devices use 1.2V as their core voltage operation with 1.0V operation also possible.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SPR 16x2 DPR 16x2	ROM 16x2

Logic Mode

In this mode, the LUTs in each Slice are configured as combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices in the PFU.

Ripple Mode

Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Up counter 2-bit
- Down counter 2-bit
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Ripple Mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per slice basis to allow fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode

In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the Slice. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

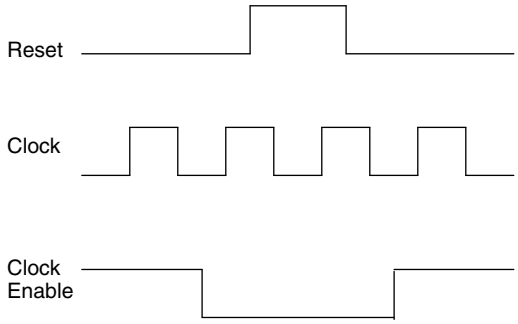
ROM Mode

The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the low-to-high transition of the reset, as shown in Figure 2-16.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM, FIFO and shift register implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-16. The reset timing rules apply to the RPReset input vs. the RE input and the RST input vs. the WE and RE inputs. Both RST and RPReset are always asynchronous EBR inputs. For the EBR shift register mode, the GSR signal is always enabled and the local RESET pin is always asynchronous.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled. For more information about on-chip memory, see TN1094, On-Chip Memory Usage Guide for LatticeSC Devices.

Programmable I/O Cells (PIC)

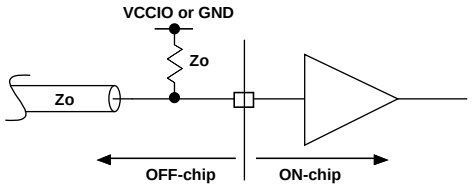
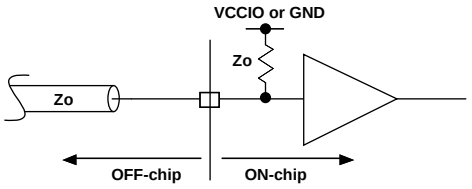
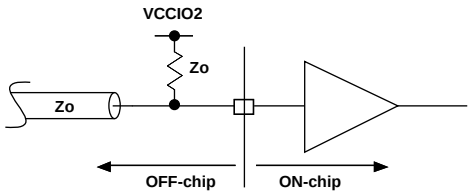
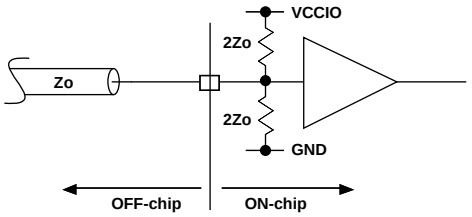
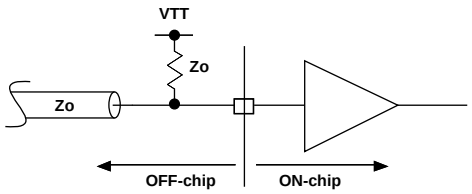
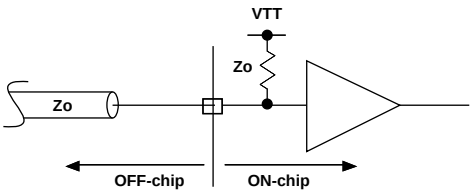
Each PIC contains four PIOs connected to their respective PURESPEED I/O Buffer which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to PURESPEED I/O buffer, and receives input (DI) from the buffer. The PIO contains advanced capabilities to allow the support of speeds up to 2Gbps. These include dedicated shift and DDR logic and adaptive input logic. The dedicated resources simplify the design of robust interfaces.

Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO}, or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

- 8-bit SERDES Only
- 10-bit SERDES Only
- SONET (STS-12/STS-48)
- Gigabit Ethernet
- Fibre Channel
- XAUI
- Serial RapidIO
- PCI-Express
- Generic 8b10b

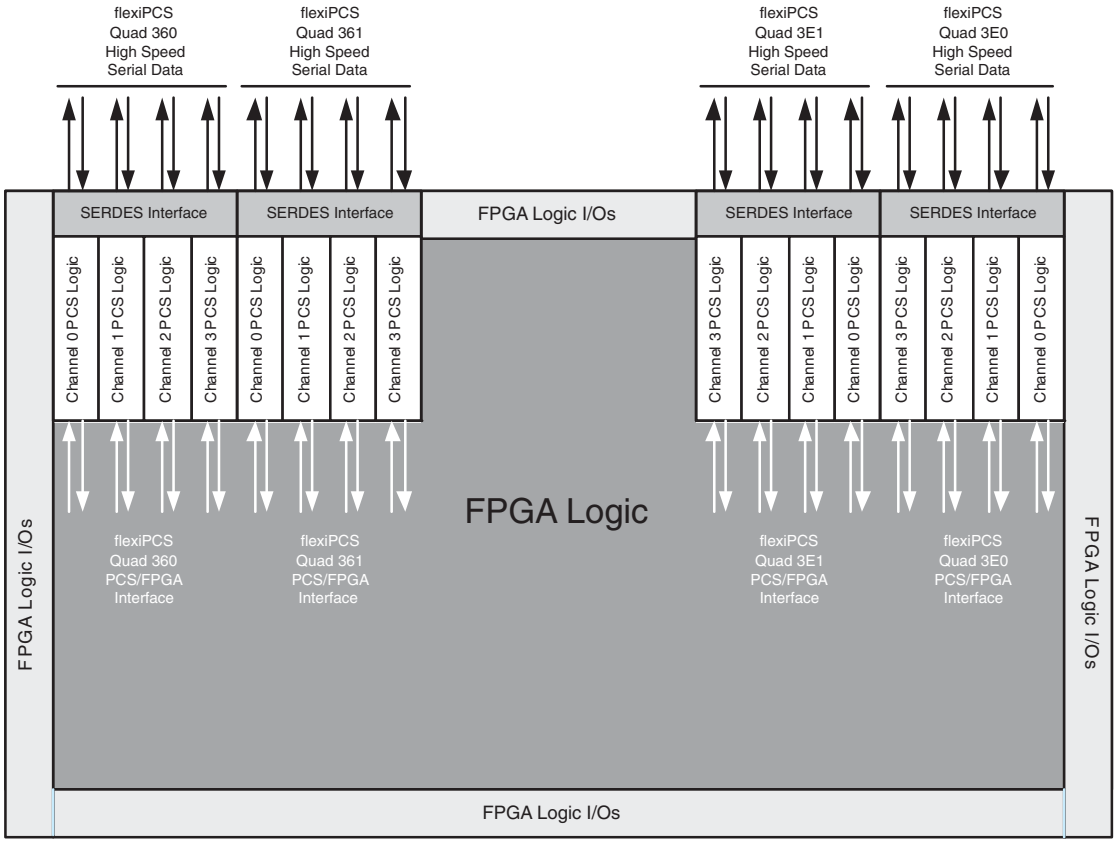
flexiPCS Quad

The flexiPCS logic is arranged in quads containing logic for four independent full-duplex data channels. Each device in the LatticeSC family has up to eight quads of flexiPCS logic. The LatticeSC Family Selection Guide table on the first page of this data sheet contains the number of flexiPCS channels present on the chip. Note that in some packages (particularly lower pin count packages), not all channels from all quads on a given device may be bonded to package pins.

Each quad supports up to four channels of full-duplex data and can be programmed into any one of several protocol based modes. Each quad requires its own reference clock which can be sourced externally or from the FPGA logic. The user can utilize between one and four channels in a quad, depending on the application.

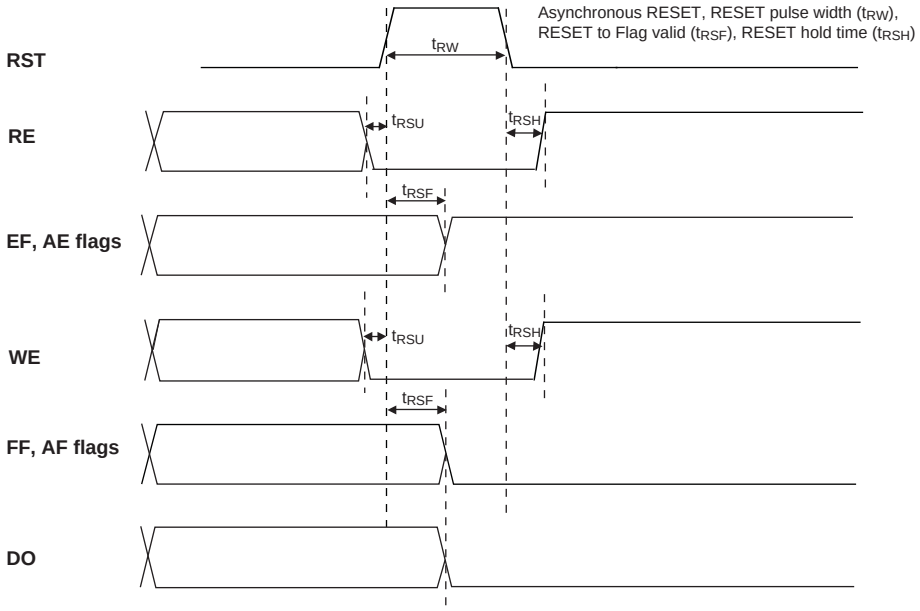
Figure 2-30 shows an example of four flexiPCS quads in a LatticeSC device. Quads are labeled according to the address of their software controlled registers.

Figure 2-30. LatticeSC flexiPCS



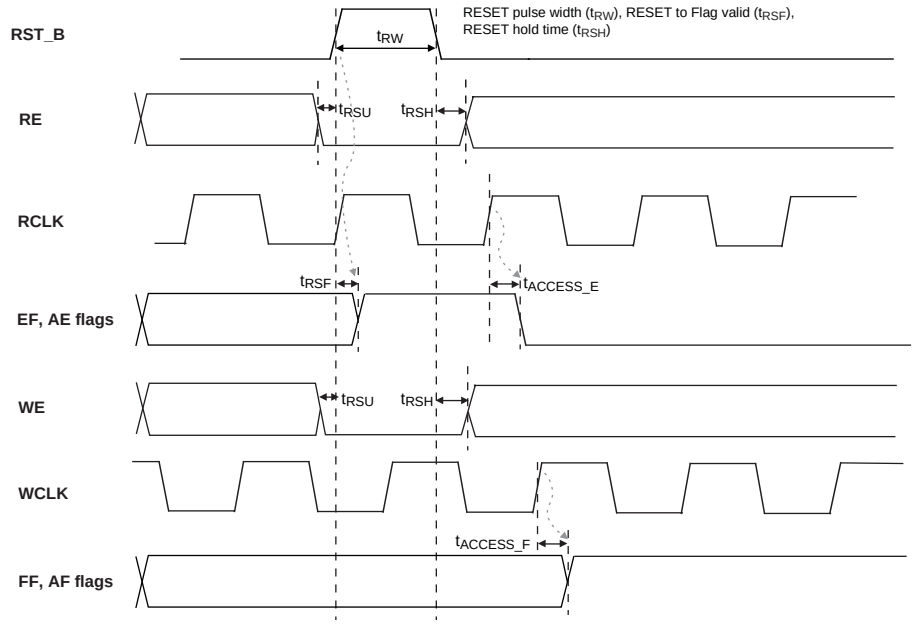
Since each quad has its own reference clock, different quads can support different standards on the same chip. This feature makes the LatticeSC family of devices ideal for bridging between different standards.

Figure 3-10. FIFO Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Figure 3-11. Read Pointer Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C32	VCC12	-		VCC12	-	
E34	NC	-		PL22A	7	
F34	NC	-		PL22B	7	
F33	NC	-		PL24A	7	
G33	NC	-		PL24B	7	
K30	NC	-		PL25A	7	
L30	NC	-		PL25B	7	
G34	NC	-		PL26A	7	
H34	NC	-		PL26B	7	
M32	NC	-		PL39A	7	
N32	NC	-		PL39B	7	
P28	NC	-		PL39C	7	
R28	NC	-		PL39D	7	
J34	NC	-		PL41A	7	
K34	NC	-		PL41B	7	
P30	NC	-		PL41C	7	
R30	NC	-		PL41D	7	
W34	NC	-		PL59A	6	
Y34	NC	-		PL59B	6	
W32	NC	-		PL61A	6	
Y32	NC	-		PL61B	6	
AA34	NC	-		PL64A	6	
AB34	NC	-		PL64B	6	
AC34	NC	-		PL67A	6	
AD34	NC	-		PL67B	6	
Y30	NC	-		PL68A	6	
AA30	NC	-		PL68B	6	
AB33	NC	-		PL69A	6	
AC33	NC	-		PL69B	6	
AC2	NC	-		PR69B	3	
AB2	NC	-		PR69A	3	
AA5	NC	-		PR68B	3	
Y5	NC	-		PR68A	3	
AD1	NC	-		PR67B	3	
AC1	NC	-		PR67A	3	
AB1	NC	-		PR64B	3	
AA1	NC	-		PR64A	3	
Y3	NC	-		PR61B	3	
W3	NC	-		PR61A	3	
Y1	NC	-		PR59B	3	
W1	NC	-		PR59A	3	
R5	NC	-		PR41D	2	
P5	NC	-		PR41C	2	
K1	NC	-		PR41B	2	
J1	NC	-		PR41A	2	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
R7	NC	-		PR39D	2	
P7	NC	-		PR39C	2	
N3	NC	-		PR39B	2	
M3	NC	-		PR39A	2	
H1	NC	-		PR26B	2	
G1	NC	-		PR26A	2	
L5	NC	-		PR25B	2	
K5	NC	-		PR25A	2	
G2	NC	-		PR24B	2	
F2	NC	-		PR24A	2	
F1	NC	-		PR22B	2	
E1	NC	-		PR22A	2	
A2	GND	-		GND	-	
A33	GND	-		GND	-	
AA15	GND	-		GND	-	
AA20	GND	-		GND	-	
AA32	GND	-		GND	-	
AA4	GND	-		GND	-	
AB28	GND	-		GND	-	
AB6	GND	-		GND	-	
AC11	GND	-		GND	-	
AC18	GND	-		GND	-	
AC25	GND	-		GND	-	
AD23	GND	-		GND	-	
AD3	GND	-		GND	-	
AD31	GND	-		GND	-	
AE12	GND	-		GND	-	
AE15	GND	-		GND	-	
AE29	GND	-		GND	-	
AE7	GND	-		GND	-	
AE9	GND	-		GND	-	
AF20	GND	-		GND	-	
AF26	GND	-		GND	-	
AG32	GND	-		GND	-	
AG4	GND	-		GND	-	
AH13	GND	-		GND	-	
AH19	GND	-		GND	-	
AH25	GND	-		GND	-	
AH7	GND	-		GND	-	
AJ10	GND	-		GND	-	
AJ16	GND	-		GND	-	
AJ22	GND	-		GND	-	
AJ28	GND	-		GND	-	
AK3	GND	-		GND	-	
AK31	GND	-		GND	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB15	VCC12	-		VCC12	-	
AB20	VCC12	-		VCC12	-	
N15	VCC12	-		VCC12	-	
N20	VCC12	-		VCC12	-	
R13	VCC12	-		VCC12	-	
R22	VCC12	-		VCC12	-	
Y13	VCC12	-		VCC12	-	
Y22	VCC12	-		VCC12	-	
AA12	VCCAUX	-		VCCAUX	-	
AA23	VCCAUX	-		VCCAUX	-	
AB12	VCCAUX	-		VCCAUX	-	
AB16	VCCAUX	-		VCCAUX	-	
AB17	VCCAUX	-		VCCAUX	-	
AB18	VCCAUX	-		VCCAUX	-	
AB19	VCCAUX	-		VCCAUX	-	
AB23	VCCAUX	-		VCCAUX	-	
AC12	VCCAUX	-		VCCAUX	-	
AC13	VCCAUX	-		VCCAUX	-	
Y19	GND	-		GND	-	
AC14	VCCAUX	-		VCCAUX	-	
AC17	VCCAUX	-		VCCAUX	-	
AC21	VCCAUX	-		VCCAUX	-	
AC22	VCCAUX	-		VCCAUX	-	
AC23	VCCAUX	-		VCCAUX	-	
M13	VCCAUX	-		VCCAUX	-	
M14	VCCAUX	-		VCCAUX	-	
M18	VCCAUX	-		VCCAUX	-	
M21	VCCAUX	-		VCCAUX	-	
M22	VCCAUX	-		VCCAUX	-	
N12	VCCAUX	-		VCCAUX	-	
N16	VCCAUX	-		VCCAUX	-	
N17	VCCAUX	-		VCCAUX	-	
N18	VCCAUX	-		VCCAUX	-	
N19	VCCAUX	-		VCCAUX	-	
N23	VCCAUX	-		VCCAUX	-	
P12	VCCAUX	-		VCCAUX	-	
P23	VCCAUX	-		VCCAUX	-	
T13	VCCAUX	-		VCCAUX	-	
T22	VCCAUX	-		VCCAUX	-	
U12	VCCAUX	-		VCCAUX	-	
U13	VCCAUX	-		VCCAUX	-	
U22	VCCAUX	-		VCCAUX	-	
V13	VCCAUX	-		VCCAUX	-	
V22	VCCAUX	-		VCCAUX	-	
V23	VCCAUX	-		VCCAUX	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AJ34	PL98A	6	
AK34	PL98B	6	
AB27	PL98C	6	
AC27	PL98D	6	
AF33	PL99A	6	
AG33	PL99B	6	
AC29	PL99C	6	
AD29	PL99D	6	
AE31	PL103A	6	
AF31	PL103B	6	
AF30	PL103C	6	
AF29	PL103D	6	
AH33	PL104A	6	
AJ33	PL104B	6	
AC28	PL104C	6	
AD28	PL104D	6	
AH32	PL107A	6	
AJ32	PL107B	6	
AD27	PL107C	6	
AE27	PL107D	6	VREF2_6
AG34	PL109A	6	
AH34	PL109B	6	
AC26	PL109C	6	
AB26	PL109D	6	
AK33	PL112A	6	
AL33	PL112B	6	
AG30	PL112C	6	
AH30	PL112D	6	
AL34	PL115A	6	
AM34	PL115B	6	
AJ30	PL115C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL115D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AJ31	PL116A	6	
AH31	PL116B	6	
AD26	PL116C	6	
AD25	PL116D	6	
AL32	PL117A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL117B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AG29	PL117C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL117D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-	
AF27	TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN33	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AH29	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AJ29	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AM32	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AM31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AG27	PB4C	5	
AG26	PB4D	5	
AL29	PB5A	5	
AL28	PB5B	5	
AH27	PB5C	5	
AH26	PB5D	5	VREF1_5
AN32	PB7A	5	
AP32	PB7B	5	
AF25	PB7C	5	
AE25	PB7D	5	
AN31	PB11A	5	
AN30	PB11B	5	
AK29	PB11C	5	
AK28	PB11D	5	
AP31	PB12A	5	
AP30	PB12B	5	
AD24	PB12C	5	
AE24	PB12D	5	
AM29	PB15A	5	
AM28	PB15B	5	
AJ27	PB15C	5	
AJ26	PB15D	5	
AP29	PB16A	5	
AP28	PB16B	5	
AK27	PB16C	5	
AK26	PB16D	5	
AN29	PB19A	5	
AN28	PB19B	5	
AG25	PB19C	5	
AG24	PB19D	5	
AL26	PB20A	5	
AL25	PB20B	5	
AG23	PB20C	5	
AG22	PB20D	5	
AN27	PB23A	5	
AN26	PB23B	5	
AF24	PB23C	5	
AF23	PB23D	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
K26	GND	-	
K28	GND	-	
K6	GND	-	
K9	GND	-	
L12	GND	-	
L32	GND	-	
L4	GND	-	
M10	GND	-	
M17	GND	-	
M24	GND	-	
N29	GND	-	
N7	GND	-	
P15	GND	-	
P20	GND	-	
P3	GND	-	
P31	GND	-	
R10	GND	-	
R14	GND	-	
R16	GND	-	
R19	GND	-	
R21	GND	-	
R26	GND	-	
T15	GND	-	
T17	GND	-	
T18	GND	-	
T20	GND	-	
T28	GND	-	
T6	GND	-	
U16	GND	-	
U19	GND	-	
U23	GND	-	
U32	GND	-	
U4	GND	-	
V12	GND	-	
V16	GND	-	
V19	GND	-	
V3	GND	-	
V31	GND	-	
W15	GND	-	
W17	GND	-	
W18	GND	-	
W20	GND	-	
W29	GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
BB12	PB88B	4		PB102B	4	
AM17	PB88C	4		PB102C	4	
AL17	PB88D	4		PB102D	4	
AW14	PB89A	4		PB103A	4	
AW13	PB89B	4		PB103B	4	
AP16	PB89C	4		PB103C	4	
AN16	PB89D	4		PB103D	4	
BA13	PB91A	4		PB105A	4	
BA12	PB91B	4		PB105B	4	
AU13	PB91C	4		PB105C	4	
AU12	PB91D	4		PB105D	4	
BB11	PB92A	4		PB106A	4	
BB10	PB92B	4		PB106B	4	
AP15	PB92C	4		PB106C	4	
AN15	PB92D	4		PB106D	4	
AV13	PB93A	4		PB107A	4	
AV12	PB93B	4		PB107B	4	
AT13	PB93C	4		PB107C	4	
AT12	PB93D	4		PB107D	4	
BA11	PB95A	4		PB109A	4	
BA10	PB95B	4		PB109B	4	
AR13	PB95C	4		PB109C	4	
AR12	PB95D	4		PB109D	4	
AY11	PB96A	4		PB110A	4	
AY10	PB96B	4		PB110B	4	
AP14	PB96C	4		PB110C	4	
AN14	PB96D	4		PB110D	4	
BB9	PB97A	4		PB111A	4	
BB8	PB97B	4		PB111B	4	
AU11	PB97C	4		PB111C	4	
AU10	PB97D	4		PB111D	4	
AW11	PB99A	4		PB113A	4	
AW10	PB99B	4		PB113B	4	
AJ16	PB99C	4		PB113C	4	
AJ17	PB99D	4		PB113D	4	
BA9	PB100A	4		PB114A	4	
BA8	PB100B	4		PB114B	4	
AM15	PB100C	4		PB114C	4	
AL15	PB100D	4		PB114D	4	
AV11	PB101A	4		PB115A	4	
AV10	PB101B	4		PB115B	4	
AP13	PB101C	4		PB115C	4	
AP12	PB101D	4		PB115D	4	
BB7	PB103A	4		PB117A	4	
BB6	PB103B	4		PB117B	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AU9	PB103C	4		PB117C	4	
AU8	PB103D	4		PB117D	4	
AY8	PB104A	4		PB118A	4	
AY7	PB104B	4		PB118B	4	
AU7	PB104C	4		PB118C	4	
AU6	PB104D	4		PB118D	4	
BA7	PB105A	4		PB119A	4	
BA6	PB105B	4		PB119B	4	
AN13	PB105C	4		PB119C	4	
AN12	PB105D	4		PB119D	4	
AV9	PB107A	4		PB121A	4	
AV8	PB107B	4		PB121B	4	
AT10	PB107C	4		PB121C	4	
AT9	PB107D	4		PB121D	4	
AW8	PB108A	4		PB122A	4	
AW7	PB108B	4		PB122B	4	
AP11	PB108C	4		PB122C	4	
AP10	PB108D	4		PB122D	4	
BB5	PB109A	4		PB123A	4	
BB4	PB109B	4		PB123B	4	
AR10	PB109C	4		PB123C	4	
AR9	PB109D	4		PB123D	4	
BA5	PB111A	4		PB125A	4	
BA4	PB111B	4		PB125B	4	
AT7	PB111C	4		PB125C	4	
AT6	PB111D	4		PB125D	4	
BB3	PB112A	4		PB126A	4	
BA3	PB112B	4		PB126B	4	
AM14	PB112C	4		PB126C	4	
AL14	PB112D	4		PB126D	4	
AY5	PB113A	4		PB127A	4	
AY4	PB113B	4		PB127B	4	
AN11	PB113C	4		PB127C	4	
AN10	PB113D	4		PB127D	4	
AV7	PB115A	4		PB129A	4	
AV6	PB115B	4		PB129B	4	
AM12	PB115C	4		PB129C	4	
AM11	PB115D	4		PB129D	4	
AW5	PB116A	4		PB130A	4	
AW4	PB116B	4		PB130B	4	
AT5	PB116C	4		PB130C	4	
AT4	PB116D	4		PB130D	4	
AY2	PB117A	4		PB131A	4	
BA2	PB117B	4		PB131B	4	
AP9	PB117C	4		PB131C	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
T16	GND	-		GND	-	
T19	GND	-		GND	-	
T24	GND	-		GND	-	
T27	GND	-		GND	-	
T32	GND	-		GND	-	
U18	GND	-		GND	-	
U20	GND	-		GND	-	
U23	GND	-		GND	-	
U25	GND	-		GND	-	
U36	GND	-		GND	-	
U7	GND	-		GND	-	
G36	GND	-		GND	-	
G7	GND	-		GND	-	
V17	GND	-		GND	-	
V19	GND	-		GND	-	
V24	GND	-		GND	-	
V26	GND	-		GND	-	
V4	GND	-		GND	-	
V40	GND	-		GND	-	
W12	GND	-		GND	-	
W16	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W23	GND	-		GND	-	
W25	GND	-		GND	-	
W27	GND	-		GND	-	
W31	GND	-		GND	-	
Y17	GND	-		GND	-	
Y19	GND	-		GND	-	
Y21	GND	-		GND	-	
Y22	GND	-		GND	-	
AA17	VCC	-		VCC	-	
AA18	VCC	-		VCC	-	
AA19	VCC	-		VCC	-	
AA21	VCC	-		VCC	-	
AA22	VCC	-		VCC	-	
AA24	VCC	-		VCC	-	
AA25	VCC	-		VCC	-	
AA26	VCC	-		VCC	-	
AB17	VCC	-		VCC	-	
AB18	VCC	-		VCC	-	
AB19	VCC	-		VCC	-	
AB21	VCC	-		VCC	-	
AB22	VCC	-		VCC	-	
AB24	VCC	-		VCC	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FF1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FF1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FF1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FC1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FC1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FC1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FF1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FF1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FF1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FC1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FC1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FC1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Lead-Free Packaging

Commercial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-7FN256C	-7	Lead-Free fpBGA	256	COM	15.2
LFSC3GA15E-6FN256C	-6	Lead-Free fpBGA	256	COM	15.2
LFSC3GA15E-5FN256C	-5	Lead-Free fpBGA	256	COM	15.2
LFSC3GA15E-7FN900C	-7	Lead-Free fpBGA	900	COM	15.2
LFSC3GA15E-6FN900C	-6	Lead-Free fpBGA	900	COM	15.2
LFSC3GA15E-5FN900C	-5	Lead-Free fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-7FN256C	-7	Lead-Free fpBGA	256	COM	15.2
LFSCM3GA15EP1-6FN256C	-6	Lead-Free fpBGA	256	COM	15.2
LFSCM3GA15EP1-5FN256C	-5	Lead-Free fpBGA	256	COM	15.2
LFSCM3GA15EP1-7FN900C	-7	Lead-Free fpBGA	900	COM	15.2
LFSCM3GA15EP1-6FN900C	-6	Lead-Free fpBGA	900	COM	15.2
LFSCM3GA15EP1-5FN900C	-5	Lead-Free fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-7FN900C	-7	Lead-Free fpBGA	900	COM	25.4
LFSC3GA25E-6FN900C	-6	Lead-Free fpBGA	900	COM	25.4
LFSC3GA25E-5FN900C	-5	Lead-Free fpBGA	900	COM	25.4
LFSC3GA25E-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	25.4
LFSC3GA25E-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	25.4
LFSC3GA25E-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	25.4
LFSC3GA25E-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-7FN900C	-7	Lead-Free fpBGA	900	COM	25.4
LFSCM3GA25EP1-6FN900C	-6	Lead-Free fpBGA	900	COM	25.4
LFSCM3GA25EP1-5FN900C	-5	Lead-Free fpBGA	900	COM	25.4
LFSCM3GA25EP1-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

LatticeSC/M Family Data Sheet Supplemental Information

January 2008 **Data Sheet DS1004**

For Further Information

For further information about the flexiPCS, see the LatticeSC/M Family flexiPCS Data Sheet.

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- LatticeSC PURESPEED I/O Usage Guide (TN1088)
- LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide (TN1158)
- LatticeSC sysCLOCK PLL/DLL User's Guide (TN1098)
- On-Chip Memory Usage Guide for LatticeSC Devices (TN1094)
- LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide (TN1099)
- LatticeSC QDRII/II+ SRAM Memory Interface User's Guide (TN1096)
- LatticeSC sysCONFIG Usage Guide (TN1080)
- LatticeSC MPI/System Bus (TN1085)
- SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices (TN1100)
- Power Estimation and Management for LatticeSC Devices (TN1101)
- LatticeSC SERDES Jitter (TN1084)
- LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks (TN1110)
- Lattice PCI Express Basic Demo User's Guide (UG08)
- LatticeSC flexiPCS/SERDES Design Guide (TN1145)
- Temperature Sensing Diode in LatticeSC Devices (TN1115)
- SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: ww.pcisig.com

Date	Version	Section	Change Summary
August 2006 (cont.)	01.3 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Family Timing Adders with ispLEVER 6.0 SP1 results
			Updated PLL Timing Parameters based on PDE testing results
			Removed RDDATA parameter from sysCONFIG readback timing table
		Multiple	Changed TDO/RDDATA to TDO
		Pinout Information	Removed all MPI signals from SC15 256 pin package Dual Function Column
			Added note to SC15, SC25 900 pin package that the package supports a 16 bit MPI
			Added note that pin D3 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note that pin D28 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note to SC25 1020 pin package that the package supports a 16 bit MPI
			Added note to SC80 1152 pin package that the package supports a 32 bit MPI
			Added note to SC80 1704 pin package that the package supports a 32 bit MPI
		Ordering Information	Changed “fcBGA” for the 1020 packages to “ffBGA”
November 2006	01.4	Introduction	LatticeSC Family Selection Guide table – I/O count for SC80 device, 1704 fcBGA package changed to 904/32. I/O count for SC115 device, 1704 fcBGA package changed to 942/32.
		DC and Switching Characteristics	DC Electrical Characteristics table – Updated the initialization and standby supply current values.
			DC Electrical Characteristics table – Updated the sysCONFIG Master Parallel mode RCLK low and RCLK high time specifications.
			DC Electrical Characteristics table – Updated VCCIO values for LVPECL33 I/Os.
		Pin Information	Pin Information Summary table - Changed number of single ended user I/Os from 906 to 904 for 1704 fcBGA.
			Removed the single-ended only output restriction on pins D3 and D28 in an SC15 and SC25 900 pin package.
		Ordering Information	Ordering Information tables - Changed number of I/Os from 906 to 904 for 1704 fcBGA.
			Added ordering part numbers for LatticeSC/SCM 40K and 115K LUT devices.
			Added lead-free ordering part numbers.
		Multiple	Changed number of available SC80 I/O from 906 to 904.
			Changed number of available SC115 I/O from 944 to 942.
January 2007	01.4a	Architecture	Added EBR Asynchronous Reset section.
February 2007	01.4b	Architecture	Updated EBR Asynchronous Reset section.
March 2007	01.5	Architecture	Added EBR asynchronous reset clarification
			Clarified that differential drivers are not supported in banks 1, 4 and 5
		DC and Switching Characteristics	Added clarification for the description of the junction temperature specification in the Absolute Maximum Ratings section.
			Updated Initialization and Standby Current table.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.1 SP1 results.

Date	Version	Section	Change Summary
September 2007	01.7	Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
November 2007	01.8	Ordering Information	Removed -7 speed grade information for 115K LUT devices in the Ordering Information tables.
January 2008	01.9	Introduction	Corrections/Additions to memory controller list (Tables 1-2).
		Architecture	AIL Overview – Modified power used by AIL block.
			PURESPEED I/O Buffer Banks – Modified VTT termination info. Added info about complimentary drivers for all banks.
			Supported Source Synchronous Interfaces – Modified data for DDRII in Table 2-11.
		DC and Switching Characteristics	Recommended Operating Conditions – Changed footnote 3.
			Initialization and Standby Supply Current – Inserted a paragraph with info regarding the table. Also updated the table.
			Typical Building Block Function Performance – Added VCC=1.2V=1.2V+/-5% above Pin to Pin Performance table.
			LatticeSC External Switching Characteristics – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 3.
			LatticeSC Family Timing Adders – Added VCC=1.2V=1.2V+/-5% above table.
			LatticeSC Internal Timing Parameters – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 1.
			GSR Timing – Added a new table for Internal System Bus Timing after GSR Timing.
			LatticeSC sysCONFIG Port Timing – Corrected sysCONFIG SPI Port information.
		Pinout Information	Signal Descriptions – Modified info for VTT_x, PROBE_VCC, and PROBE_GND. Modified info for [LOC]_DLL[T,C]_IN[C,D,E,F].
		Supplemental Information	Updated list of technical notes, added reference to LatticeSC/M flexiPCS Data Sheet.
March 2008	02.0	DC and Switching Characteristics	Updated Internal Timing Parameters table.
			Updated Read Mode timing diagram.
			Updated Read Mode with Input Registers Only timing diagram.
June 2008	02.1	—	Data sheet status changed from preliminary to final.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		DC and Switching Characteristics	Updated LatticeSC/M External Switching Characteristics table.
			Updated LatticeSC/M Internal Timing Parameters table.
			Removed Read-Before-Write sysMEM EBR mode.
December 2008	02.2	Architecture	Output/Tristate DDR/Shift Register Block Diagram - corrected connection to POS.
		DC and Switching Characteristics	DC and Switching Characteristics table - updated data for $t_{SUI\_PIO.}$
			Added $T_{R,}$ T_F parameter to PURESPEED I/O Differential Electrical Characteristics (LVDS) table.
		Multiple	Removed references to HyperTransport throughout the data sheet.
January 2010	02.3	Introduction	Updated per PCN #01A-10 (ceramic fcBGA conversion to organic fcBGA for the 1152-ball and 1704-ball fcBGA packages) and PCN #02A-10 (1020-ball organic fcBGA conversion to 1020-ball organic fcBGA revision 2 package).
		Ordering Information	